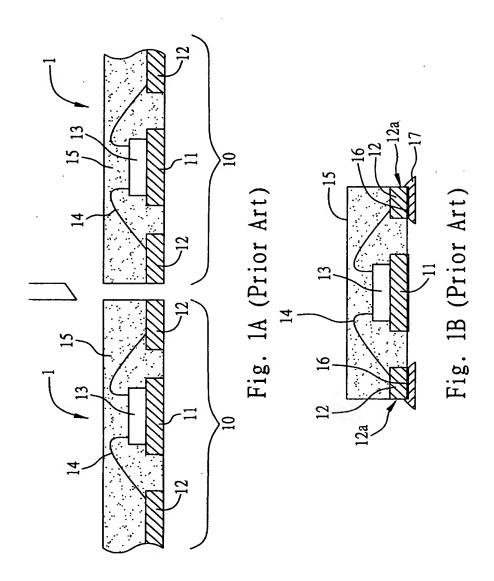
Page 1 of 10

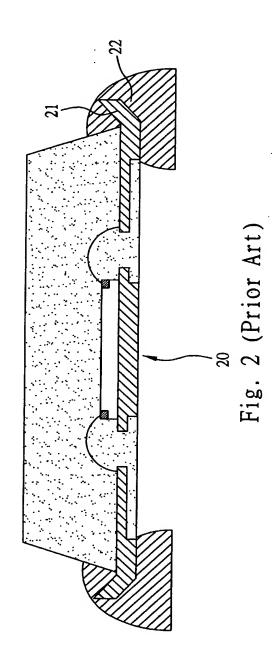
Title: SURFACE-MOUNT-ENHANCED LEAD
FRAME AND METHOD FOR FABRICATING
SEMICONDUCTOR PACKAGE WITH THE
SAME
Inventors: Te-Haw Lee, et al.
Docket No.: 1007-043
Contact: Mikio Ishimaru (408) 738-0592



Page 2 of 10

Title: SURFACE-MOUNT-ENHANCED LEAD FRAME AND METHOD FOR FABRICATING SEMICONDUCTOR PACKAGE WITH THE SAME

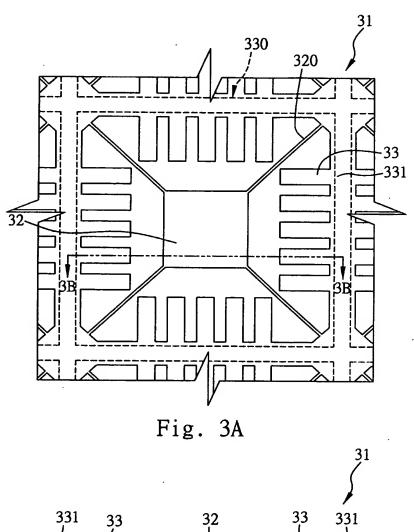
Inventors: Te-Haw Lee, et al. Docket No.: 1007-043 Contact: Mikio Ishimaru



rage 3 of 10

Title: SURFACE-MOUNT-ENHANCED LEAD FRAME AND METHOD FOR FABRICATING SEMICONDUCTOR PACKAGE WITH THE

Inventors: Te-Haw Lee, et al. Docket No.: 1007-043 Contact: Mikio Ishimaru



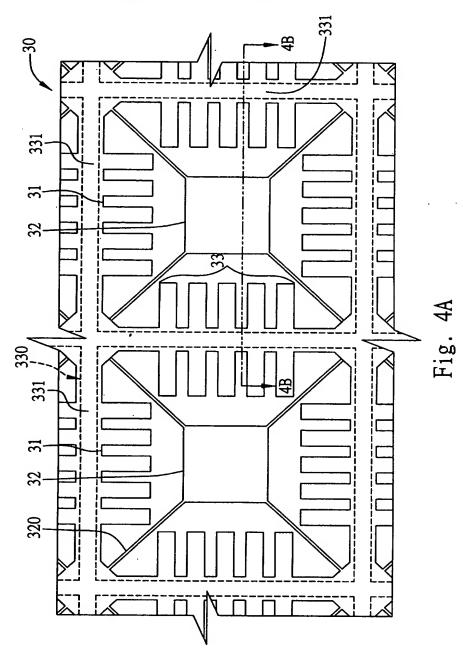
330--330 36 36 Fig. 3B

3/10

Page 4 of 10

Title: SURFACE-MOUNT-ENHANCED LEAD
FRAME AND METHOD FOR FABRICATING
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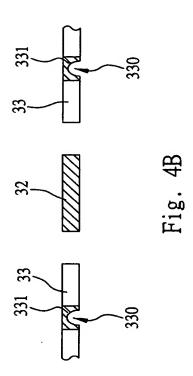


Page 5 of 10

Title: SURFACE-MOUNT-ENHANCED LEAD FRAME AND METHOD FOR FABRICATING SEMICONDUCTOR PACKAGE WITH THE

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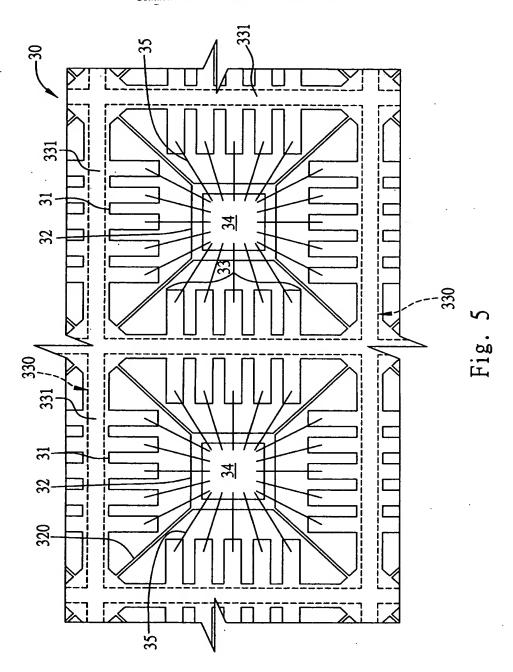
Inventors: Te-Haw Lee, et al.
Docket No.: 1007-043
Contact: Mikio Ishimaru



Page 6 of 10

Title: SURFACE-MOUNT-ENHANCED LEAD FRAME AND METHOD FOR FABRICATING SEMICONDUCTOR PACKAGE WITH THE SAME

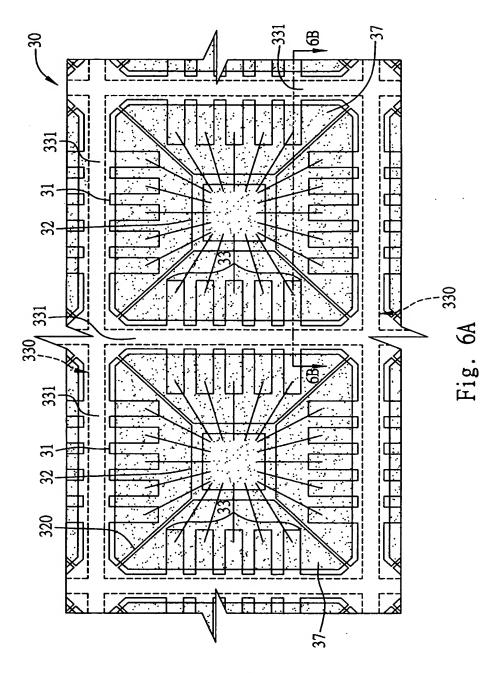
Inventors: Te-Haw Lee, et al. Docket No.: 1007-043 Contact: Mikio Ishimaru



Page 7 of 10

Title: SURFACE-MOUNT-ENHANCED LEAD FRAME AND METHOD FOR FABRICATING SEMICONDUCTOR PACKAGE WITH THE SAME

Inventors: Te-Haw Lee, et al. Docket No.: 1007-043 Contact: Mikio Ishimaru

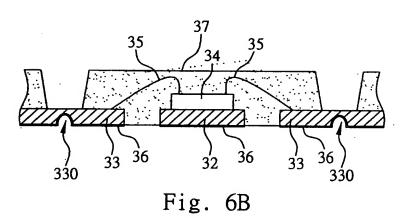


7/10

Page 8 of 10

SURFACE-MOUNT-ENHANCED LEAD FRAME AND METHOD FOR FABRICATING SEMICONDUCTOR PACKAGE WITH THE SAME Title:

Inventors: Te-Haw Lee, et al. Docket No.: 1007-043 Contact: Mikio Ishimaru



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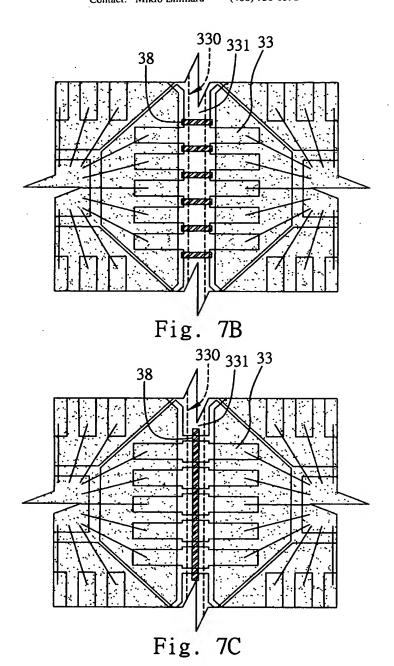
Fig. 7A

Page 9 of 10

Title: SURFACE-MOUNT-ENHANCED LEAD FRAME AND METHOD FOR FABRICATING SEMICONDUCTOR PACKAGE WITH THE

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Inventors: Te-Haw Lee, et al. Docket No.: 1007-043 Contact: Mikio Ishimaru



9/10

Page 10 of 10

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